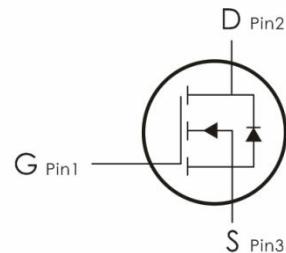
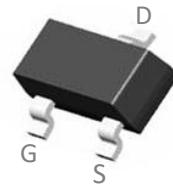


Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=30V, I_D=4A, R_{DS(on)}<38m\Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.

Absolute Maximum Ratings: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_A=25^\circ C$	4	A
	Continuous Drain Current- $T_A=100^\circ C$	2.6	
I_{DM}	Pulse Drain Current Tested ^{note1}	16	A
P_D	Power Dissipation- $T_A=25^\circ C$	1	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\Theta JA}$	Thermal Resistance,Junction to Ambient	125	$^\circ C/W$

Package Marking and Ordering Information:

Part NO.	Marking	Package
DO3406A	3406A	SOT-23

Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250 \mu\text{A}$	30	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_D=250 \mu\text{A}$	1	1.5	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance ^{note2}	$V_{\text{GS}}=10\text{V}, I_D=4\text{A}$	---	29	38	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=3\text{A}$	---	45	65	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	230	---	pF
C_{oss}	Output Capacitance		---	40	---	
C_{rss}	Reverse Transfer Capacitance		---	30	---	
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=15\text{V}, I_D=4\text{A}, V_{\text{GS}}=10\text{V}, R_G=3 \Omega$	---	4	---	ns
t_r	Rise Time		---	2.1	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	15	---	ns
t_f	Fall Time		---	3.2	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V}, I_D=2\text{A}$	---	3	---	nC
Q_{gs}	Gate-Source Charge		---	0.5	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	0.8	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Forward Voltage	$V_{\text{GS}}=0\text{V}, I_s=-4\text{A}$	---	---	1.2	V
I_s	Source drain current(Body Diode)	---	---	---	4	A

I_{SM}	Source Diode Forward Current	---	---	---	16	A
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Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Characteristics: (T_c=25°C unless otherwise noted)

Figure 1: Output Characteristics

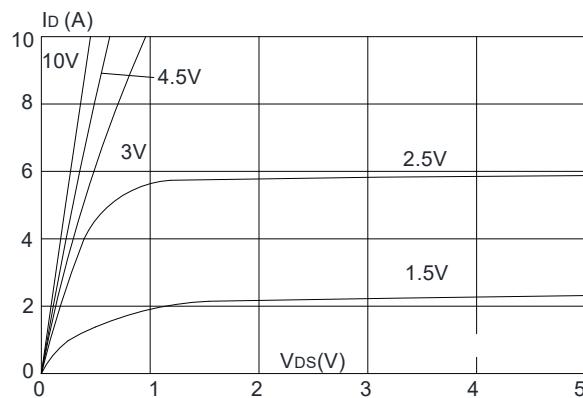


Figure 2: Typical Transfer Characteristics

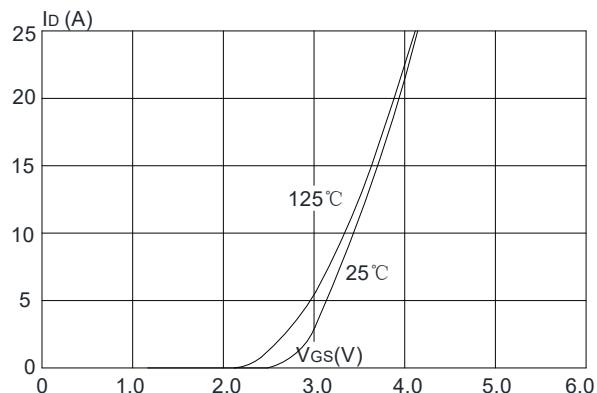


Figure 3: On-resistance vs. Drain Current

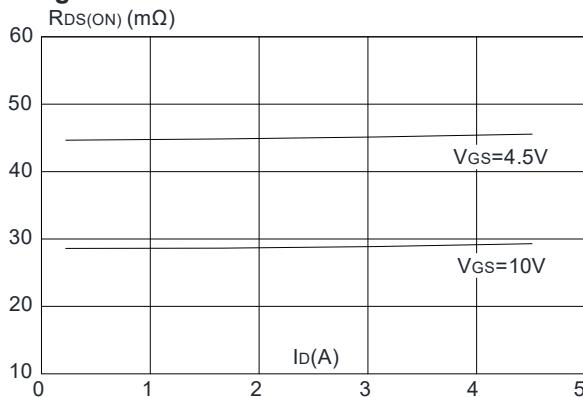


Figure 5: Gate Charge Characteristics

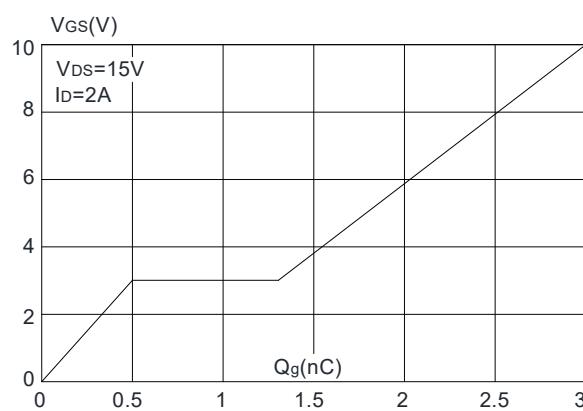


Figure 4: Body Diode Characteristics

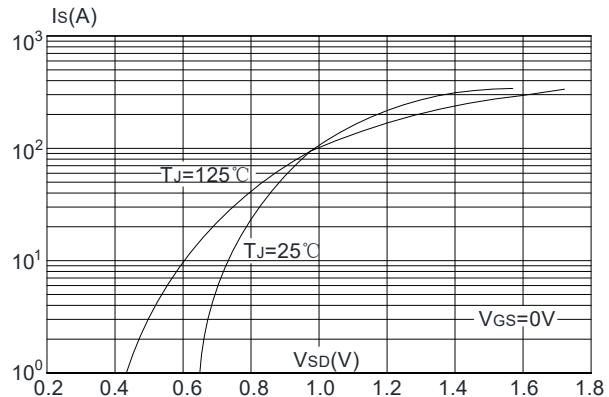


Figure 6: Capacitance Characteristics

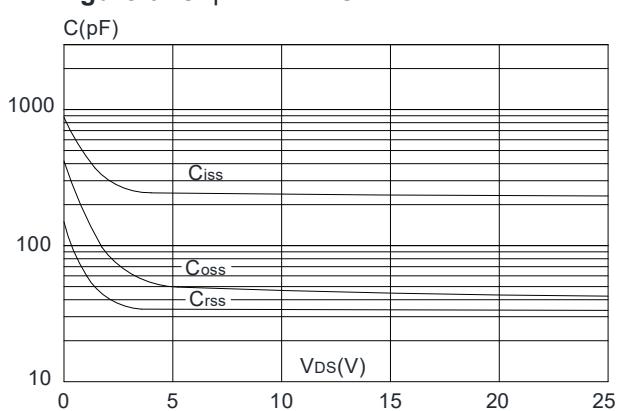


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

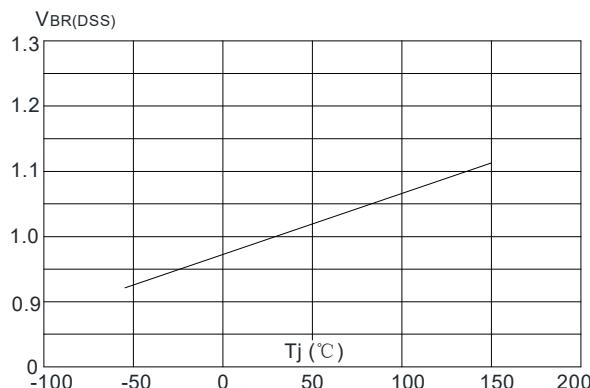


Figure 9: Maximum Safe Operating Area

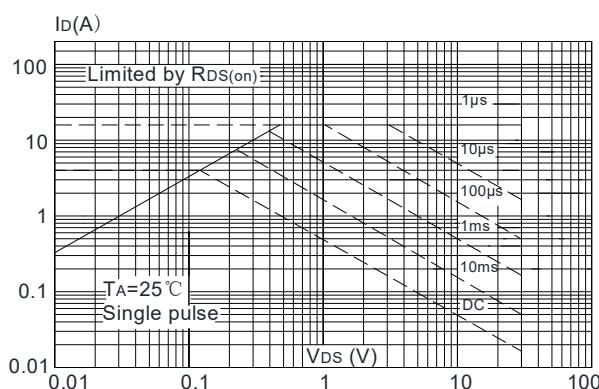


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

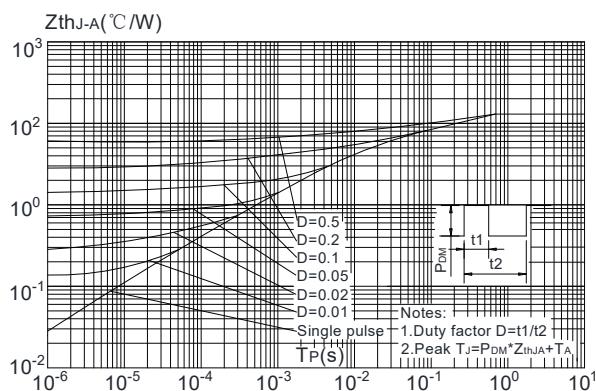


Figure 8: Normalized on Resistance vs. Junction Temperature

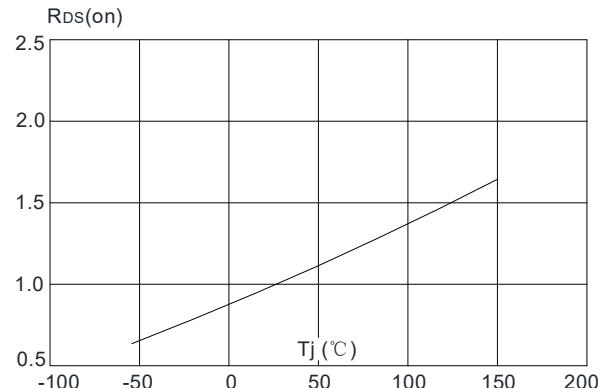


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

